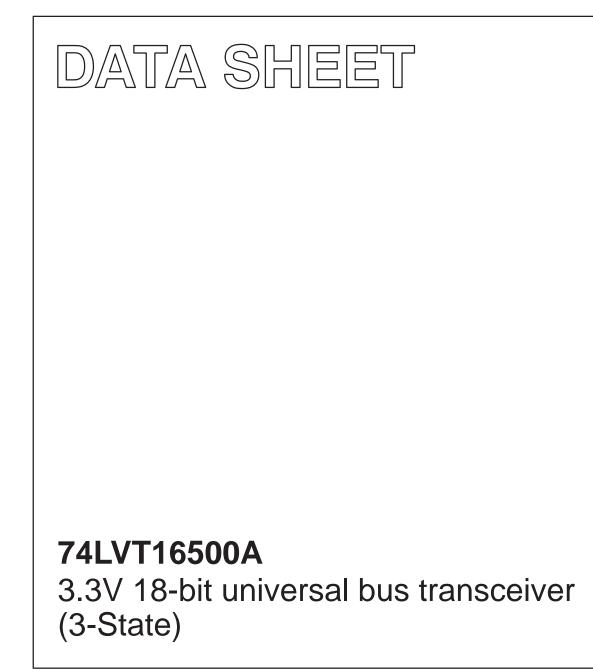
INTEGRATED CIRCUITS



Product specification Supersedes data of 1997 Jun 12 IC23 Data Handbook

1998 Feb 19





74LVT16500A

FEATURES

- 18-bit bidirectional bus interface
- 3-State buffers
- Output capability: +64mA/-32mA
- TTL input and output switching levels
- Input and output interface capability to systems at 5V supply
- Bus-hold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Live insertion/extraction permitted
- Power-up reset
- Power-up 3-State
- No bus current loading when output is tied to 5V bus
- Negative edge-triggered clock inputs
- Latch-up protection exceeds 500mA per JEDEC JC40.2 Std 17
- ESD protection exceeds 2000V per MIL STD 883 Method 3015 and 200V per Machine Model

QUICK REFERENCE DATA

DESCRIPTION

The 74LVT16500A is a high-performance BiCMOS product designed for V_{CC} operation at 3.3V.

This device is an 18-bit universal transceiver featuring non-inverting 3-State bus compatible outputs in both send and receive directions. Data flow in each direction is controlled by output enable (OEAB and OEBA), latch enable (LEAB and LEBA), and clock (CPAB and CPBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is High. When LEAB is Low, the A data is latched if CPAB is held at a High or Low logic level. If LEAB is Low, the A-bus data is stored in the latch/flip-flop on the High-to-Low transition of CPAB. When OEAB is High, the outputs are active. When OEAB is Low, the outputs are in the high-impedance state.

Data flow for B-to-A is similar to that of A-to-B but uses \overline{OEBA} , LEBA and \overline{CPBA} . The output enables are complimentary (OEAB is active High, and \overline{OEBA} is active Low).

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25°C	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay An to Bn or Bn to An	$C_L = 50 pF;$ $V_{CC} = 3.3 V$	1.9	ns
C _{IN}	Input capacitance (Control pins)	$V_{I} = 0V \text{ or } 3.0V$	3	pF
C _{I/O}	I/O pin capacitance	Outputs disabled; $V_{I/O} = 0V \text{ or } 3.0V$	9	pF
I _{CCZ}	Total supply current	Outputs disabled; $V_{CC} = 3.6V$	70	μΑ

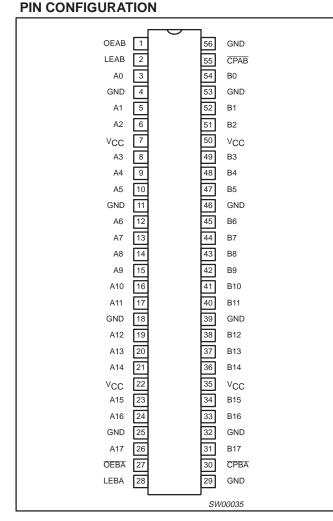
ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
56-Pin Plastic SSOP Type III	–40°C to +85°C	74LVT16500A DL	VT16500A DL	SOT371-1
56-Pin Plastic TSSOP Type II	–40°C to +85°C	74LVT16500A DGG	VT16500A DGG	SOT364-1

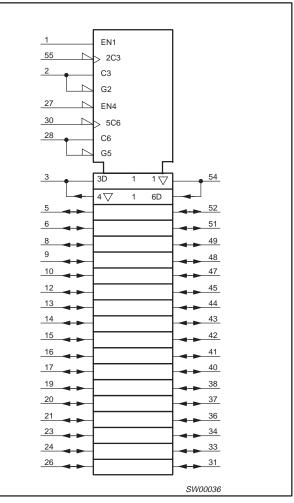
PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1	OEAB	A-to-B Output enable input
27	OEBA	B-to-A Output enable input (active low)
2, 28	LEAB/LEBA	A-to-B/B-to-A Latch enable input
55,30	CPAB/CPBA	A-to-B/B-to-A Clock input (active falling edge)
3, 5, 6, 8, 9, 10, 12, 13, 14, 15, 16, 17, 19, 20, 21, 23, 24, 26	A0-A17	Data inputs/outputs (A side)
54, 52, 51, 49, 48, 47, 45, 44, 43, 42, 41, 40, 38, 37, 36, 34, 33, 31	B0-B17	Data inputs/outputs (B side)
4, 11, 18, 25, 32, 39, 46, 53	GND	Ground (0V)
7, 22, 35, 50	V _{CC}	Positive supply voltage

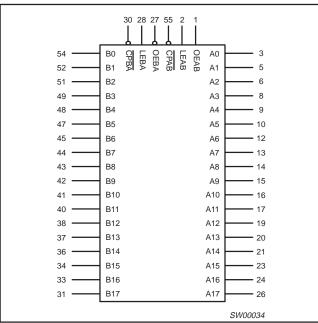
74LVT16500A



LOGIC SYMBOL (IEEE/IEC)



LOGIC SYMBOL



74LVT16500A

	INP	UTS		Internal	OUTPUTS	OPERATING MODE
OEAB	LEAB	CPAB	An	Registers	Bn	
L	н	Х	Х	Х	Z	Disabled
L	\downarrow	Х	h	н	Z	Dischlad Latch data
L	\downarrow	Х	I	L	Z	Disabled, Latch data
L	L	H or L	Х	NC	Z	Disabled, Hold data
L	L	\downarrow	h	н	Z	Disabled Cleak data
L	L	\downarrow	I	L	Z	Disabled, Clock data
Н	Н	Х	Н	н	н	Transporent
н	н	Х	L	L	L	Transparent
Н	\downarrow	Х	h	н	н	Latab data & diaplay
н	\downarrow	Х	Ι	L	L	Latch data & display
н	L	\downarrow	h	н	н	Cleak data & diaplay
н	L	\downarrow	Ι	L	L	Clock data & display
н	L	H or L	Х	н	н	Hold data & diaplay
н	L	H or L	Х	L	L	Hold data & display

NOTE: A-to-B data flow is shown; B-to-A flow is similar but uses OEBA, LEBA, and CPBA.

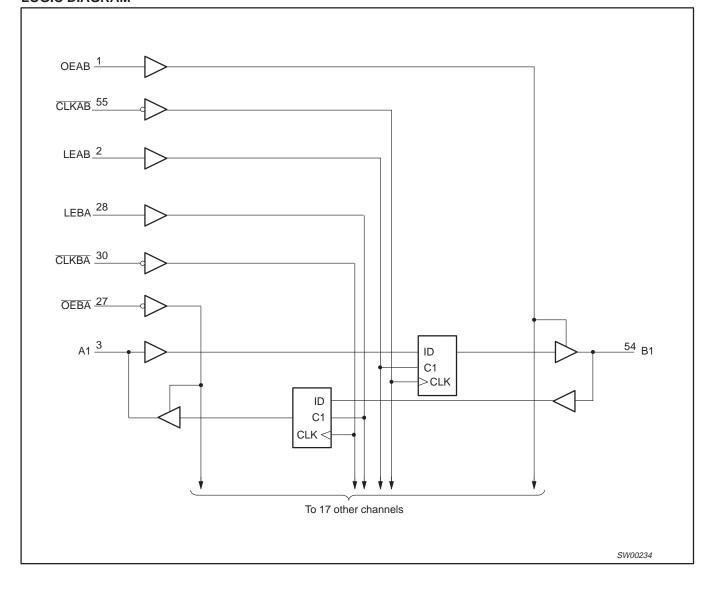
H = High voltage level h = High voltage level one set-up time prior to the Enable or Clock transition

L = Low voltage level

I = Low voltage level one set-up time prior to the Enable or Clock transition NC= No Change

 $\begin{array}{l} X = Don't \mbox{ care} \\ Z = High \mbox{ Impedance "off" state} \\ \downarrow = High-to-Low \mbox{ Enable or Clock transition} \end{array}$

LOGIC DIAGRAM



74LVT16500A

ABSOLUTE MAXIMUM RATINGS^{1, 2}

Philips Semiconductors

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +4.6	V
I _{IK}	DC input diode current	V ₁ < 0	-50	mA
VI	DC input voltage ³		-0.5 to +7.0	V
I _{OK}	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	Output in Off or High state	-0.5 to +7.0	V
		Output in Low state	128	
IOUT	DC output current	Output in High state	-64	mA
T _{stg}	Storage temperature range		-65 to +150	°C

NOTES:

Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to

absolute-maximum-rated conditions for extended periods may affect device reliability.The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

3. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	ITS	UNIT
STWBUL			MAX	UNIT
V _{CC}	DC supply voltage	2.7	3.6	V
VI	Input voltage	0	5.5	V
V _{IH}	High-level input voltage	2.0		V
V _{IL}	Input voltage		0.8	V
I _{ОН}	High-level output current		-32	mA
	Low-level output current		32	mA
I _{OL}	Low-level output current; current duty cycle \leq 50%; f \geq 1kHz		64	ma
Δt/Δv	Input transition rise or fall rate; Outputs enabled		10	ns/V
T _{amb}	Operating free-air temperature range	-40	+85	°C

DC ELECTRICAL CHARACTERISTICS

					LIMITS		
SYMBOL	PARAMETER	TEST CONDITIONS		Temp = -40°C to +85°C			UNIT
				MIN	TYP ¹	МАХ	1
V _{IK}	Input clamp voltage	$V_{CC} = 2.7V; I_{IK} = -18mA$			85	-1.2	V
		$V_{CC} = 2.7$ to 3.6V; $I_{OH} = -100\mu A$		V _{CC} -0.2	V _{CC}		
V _{OH}	High-level output voltage	$V_{CC} = 2.7V; I_{OH} = -8mA$		2.4	2.55		V
		$V_{CC} = 3.0V; I_{OH} = -32mA$		2.0	2.30		
		$V_{CC} = 2.7V; I_{OL} = 100 \mu A$			0.07	0.2	
		$V_{CC} = 2.7V; I_{OL} = 24mA$			0.3	0.5	
V _{OL}	Low-level output voltage	V _{CC} = 3.0V; I _{OL} = 16mA			0.25	0.4	V
		V _{CC} = 3.0V; I _{OL} = 32mA			0.3	0.5	
		$V_{CC} = 3.0V; I_{OL} = 64mA$			0.36	0.55	
V _{RST}	Power-up output low voltage ⁵	V_{CC} = 3.6V; I_{O} = 1mA; V_{I} = GND or V_{CC}			0.1	0.55	V
		V_{CC} = 3.6V; V_{I} = V_{CC} or GND	Control pipe		0.1	±1	
		$V_{CC} = 0 \text{ or } 3.6 \text{V}; \text{ V}_{\text{I}} = 5.5 \text{V}$	Control pins		0.1	10	
I _I	Input leakage current	$V_{CC} = 3.6V; V_1 = 5.5V$			1.0	20	μA
		$V_{CC} = 3.6V; V_I = V_{CC}$	I/O Data pins ⁴		0.1	10	
		$V_{CC} = 3.6V; V_1 = 0$	1		0.1	-5	
I _{OFF}	Output off current	$V_{CC} = 0V$; V_{I} or $V_{O} = 0$ to 4.5V			1.0	±100	μA
		$V_{CC} = 3V; V_1 = 0.8V$		75	130		
I _{HOLD}	Bus Hold current A or B outputs7	$V_{CC} = 3V; V_1 = 2.0V$		-75	-130		μA
		$V_{CC} = 0V$ to 3.6V; $V_{CC} = 3.6V$		±500			
I_{EX}	Current into an output in the High state when $V_O > V_{CC}$	V _O = 5.5V; V _{CC} = 3.0V			50	125	μA
I _{PU/PD}	Power up/down 3-State output current ³	$V_{CC} \le 1.2V$; $V_0 = 0.5V$ to V_{CC} ; $V_1 = GND$ or V_{CC} ; $OE/OE = Don't$ care			40	±100	μA
I _{CCH}		$V_{CC} = 3.6V$; Outputs High, $V_I = GND$ or V_{CC}	$V_{CC, I_O} = 0$		0.07	0.12	
I _{CCL}	Quiescent supply current	$V_{CC} = 3.6V$; Outputs Low, $V_I = GND$ or V_{CC} , $I_O = 0$			4	6	mA
I _{CCZ}	1	$V_{CC} = 3.6V$; Outputs Disabled; $V_I = GNE$	0 or $V_{CC, I_0} = 0^6$		0.07	0.12	1
ΔI_{CC}	Additional supply current per input pin ²	$V_{CC} = 3V$ to 3.6V; One input at V_{CC} -0.6V Other inputs at V_{CC} or GND	Ι,		0.1	0.2	mA

NOTES:
1. All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.
2. This is the increase in supply current for each input at the specified voltage level other than V_{CC} or GND
3. This parameter is valid for any V_{CC} between 0V and 1.2V with a transition time of up to 10msec. From V_{CC} = 1.2V to V_{CC} = 3.3V ± 0.3V a transition time of 100µsec is permitted. This parameter is valid for T_{amb} = 25°C only.
4. Unused pins at V_{CC} or GND.
5. For valid test results, data must not be loaded into the flip-flops (or latches) after applying power.
6. Loaz is measured with outputs nulled to V_{CC} or GND.

6. I_{CCZ} is measured with outputs pulled to V_{CC} or GND. 7. This is the bus hold overdrive current required to force the input to the opposite logic state.

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AC CHARACTERISTICS

GND = 0V; $t_R = t_F = 2.5ns$; $C_L = 50pF$; $R_L = 500\Omega$; $T_{amb} = -40^{\circ}C$ to $+85^{\circ}C$.

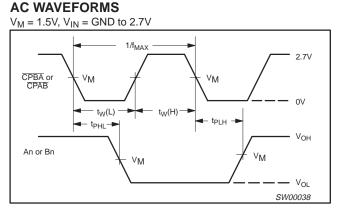
SYMBOL	PARAMETER	WAVEFORM	V _{CC} = 3.3V ±0.3V			V _{CC} = 2.7V	UNIT
			MIN	TYP ¹	MAX	MAX	1
f _{MAX}	Maximum clock frequency	1	150	350			MHz
t _{PLH} t _{PHL}	Propagation delay An to Bn or Bn to An	2	0.5 0.5	1.9 1.9	4.2 4.2	5.4 5.4	ns
t _{PLH} t _{PHL}	Propagation delay CPAB to Bn or CPBA to An	1	1.0 1.0	3.2 3.2	5.4 5.4	6.4 6.4	ns
t _{PLH} t _{PHL}	Propagation delay LEAB to Bn or LEBA to An	3	1.0 1.0	2.4 2.9	5.4 5.4	6.4 6.4	ns
t _{PZH} t _{PZL}	Output enable time to High and Low level	5 6	1.0 1.0	2.4 2.2	3.9 3.9	4.6 5.2	ns
t _{PHZ} t _{PLZ}	Output disable time from High and Low Level	5 6	1.0 1.0	2.8 3.2	5.2 5.2	5.6 5.6	ns

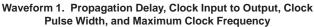
NOTE: 1. All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

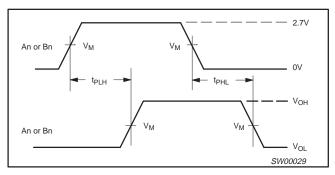
AC SETUP REQUIREMENTS

GND = 0V; $t_R = t_F = 2.5ns$; $C_L = 50pF$, $R_L = 500\Omega$; $T_{amb} = -40^{\circ}C$ to +85°C.

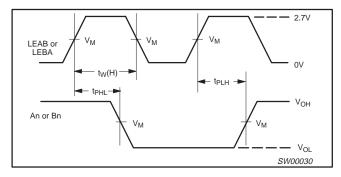
				LIMITS		
SYMBOL	PARAMETER	WAVEFORM	V _{CC} = 3.3	3V ±0.3V	V _{CC} = 2.7V	UNIT
			MIN	TYP	MIN	
ts(H) ts(L)	Setup time, High or Low An to CPAB or Bn to CPBA	4	1.8 1.8	1.0 0.7	1.5 1.5	ns
th(H) th(L)	Hold time, High or Low An to CPAB or Bn to CPBA	4	0 0	0 0	0 0	ns
ts(H) ts(L)	Setup time, High or Low An to LEAB or Bn to CPBA	4	1.8 1.8	1.1 0.8	1.5 1.5	ns
th(H) th(L)	Hold time, High or Low An to LEAB or Bn to LEBA	4	0 0	0 0	0 0	ns
tw(H) tw(L)	Pulse width, High or Low CPAB or CPBA	1	1.2 1.2	0.8 0.8	1.5 1.5	ns
tw(H)	LEAB or LEBA pulse width, High	3	1.2	0.8	1.5	ns



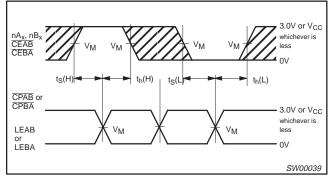




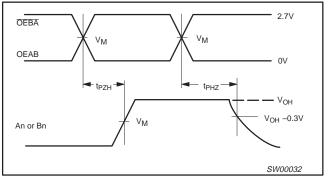
Waveform 2. Propagation Delay, Transparent Mode



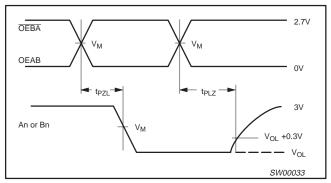
Waveform 3. Propagation Delay, Enable to Output, and Enable Pulse Width



Waveform 4. Data Setup and Hold Times



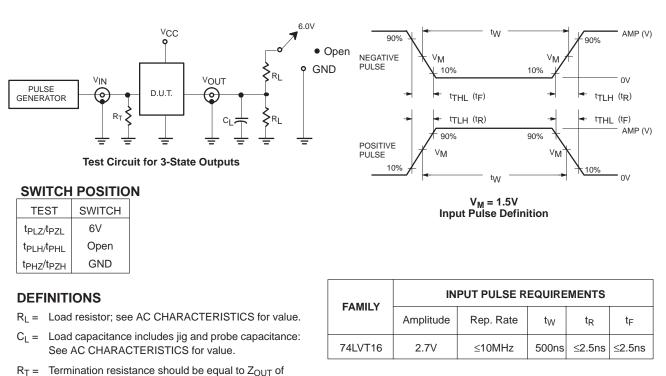
Waveform 5. 3-State Output Enable Time to High Level and Output Disable Time from High Level



Waveform 6. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level

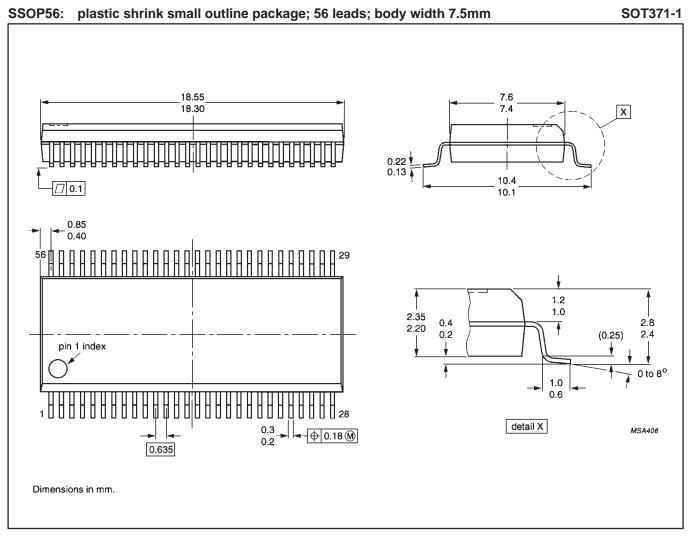
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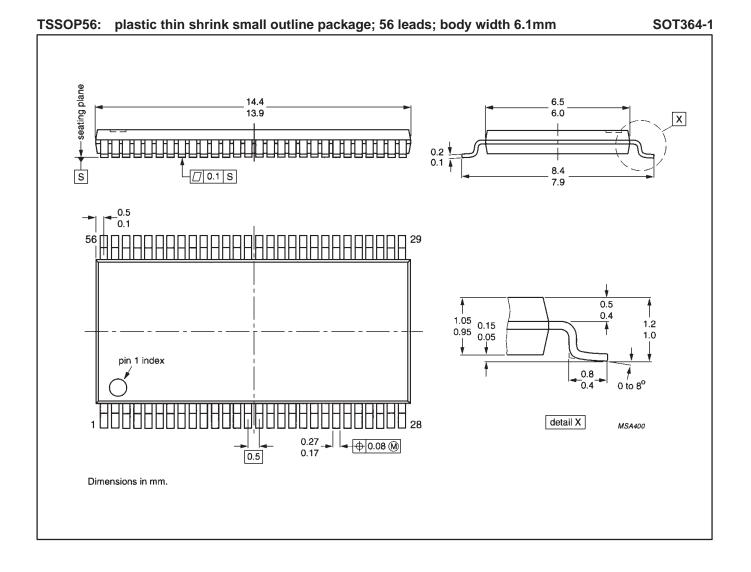
TEST CIRCUIT AND WAVEFORMS



R_T = Termination resistance should be equal to Z_{OUT} pulse generators.

SW00040





74LVT16500A

NOTES

74LVT16500A

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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Limiting values definition - Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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